



LUND
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EITF35: Introduction to Structured VLSI Design

Part 1.1.2: Introduction (Digital VLSI Systems)

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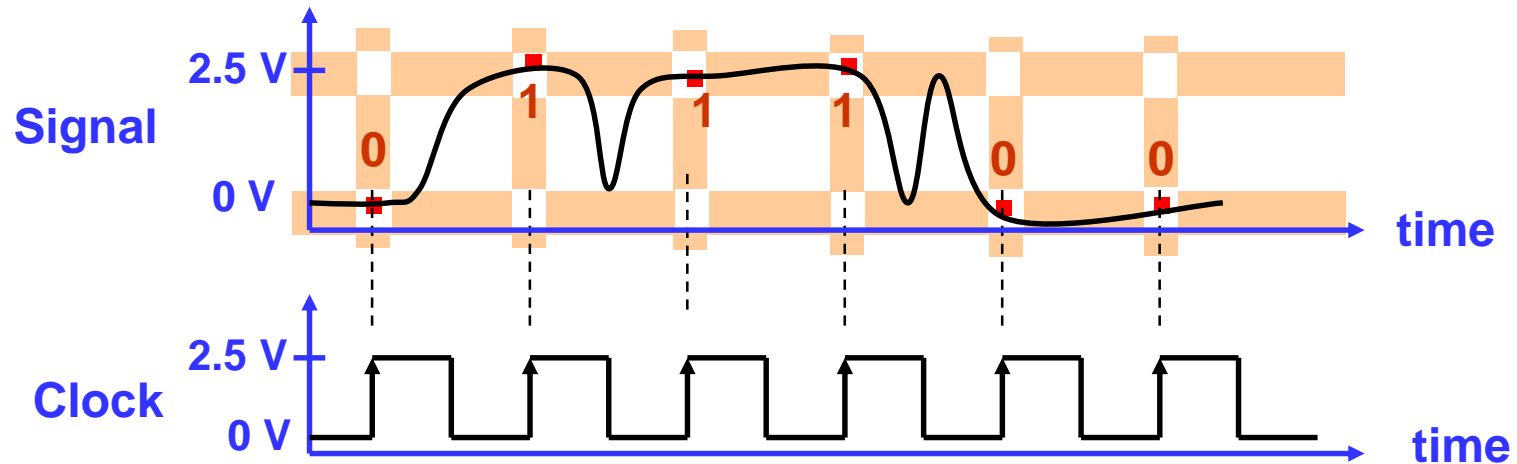


Outline

- **Why Digital?**
- **History & Roadmap**
- **Device Technology & Platforms**
- **System Representation**
- **Design Flow**
- **RTL (register transfer level) Basics**



Digitalization



□ Digital is an abstraction

- Discrete in time: **Sampling**
- Discrete in value: **Quantization**

□ Digital vs. Analog

- Flexibility & functionality: easier to store and manipulate information
- Reliability: tolerant to noise, mismatch, variations, etc.
- Economic: “easy” to design, and friendly to technology evolvement



Applications 4C:CCCC



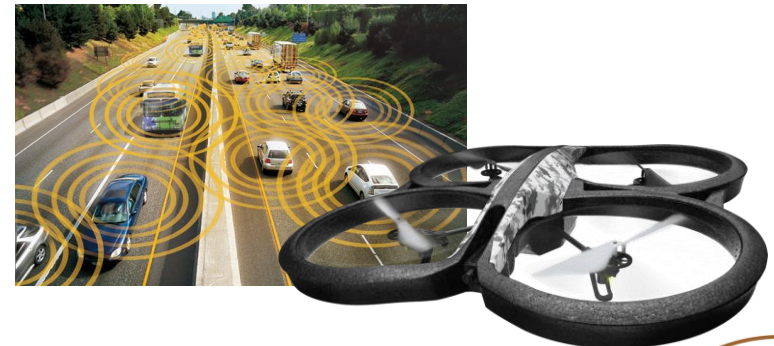
Computation



Communication



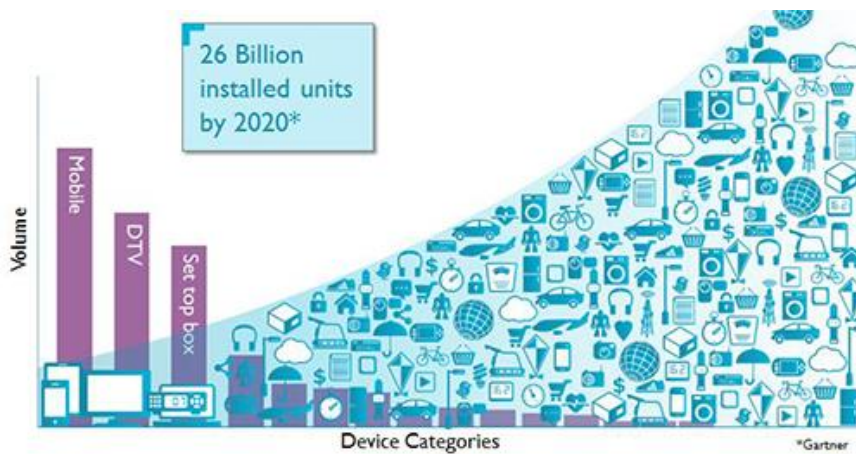
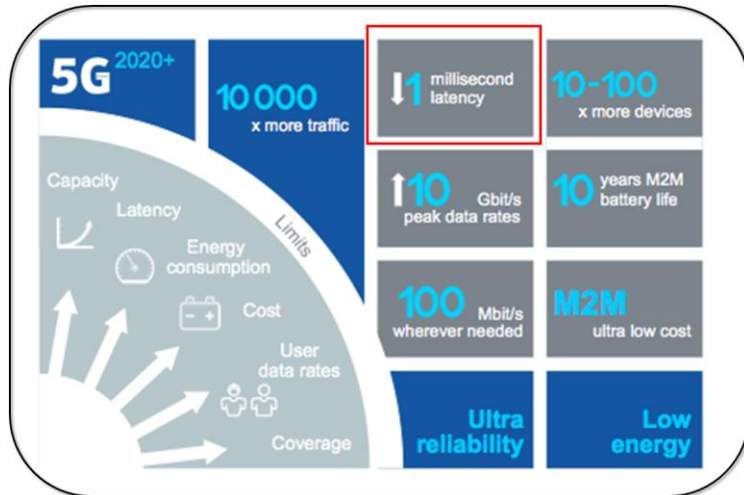
Consumer



Control



Coming soon



Outline

□ Why Digital?

- Advantages
- Some applications

□ History & Roadmap

□ Device Technology & Platforms

□ System Representation

□ Design Flow

□ RTL Basics



Brief History

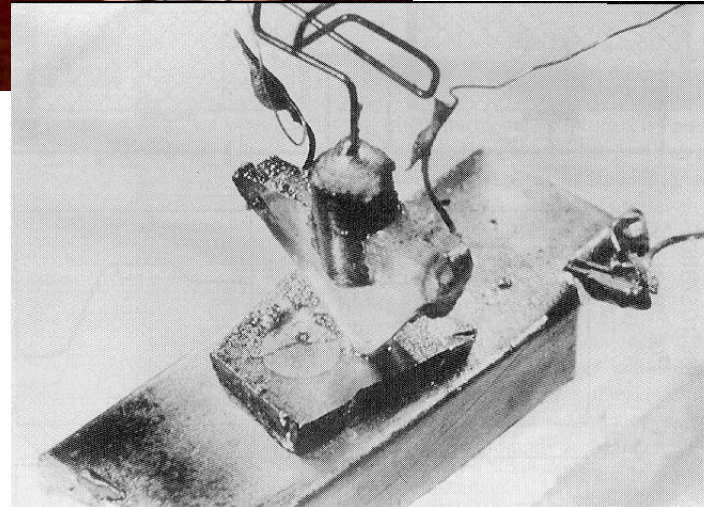
□ Transistor Evolution

- First Transistor
 - *Bell Labs (1947)*
 - *Bardeen, Brattain, Shockley*
 - *Nobel Prize (1956)*



□ Integration Evolution

- First Integrated circuit
 - *Jack Kilby*
 - *TI (1960)*
 - *Nobel Prize (2000)*



Material ...
of the
ely



Technology Evolution

□ Bipolar

- Transistor
 - 1947, *Bardeen/Bell Lab*
- Bipolar junction transistor
 - 1949, *William Shockley*
- Logic gate
 - 1956, *Harris*
- Integrated circuit
 - 1958, *Kilby/Noyes*
- Transistor–transistor logic (TTL)
 - 1962, *James L. Buie*
- High-speed Emitter-coupled logic (ECL)
 - 1974, *Masaki*

□ MOSFET (metal-oxide-semiconductor field-effect transistor)

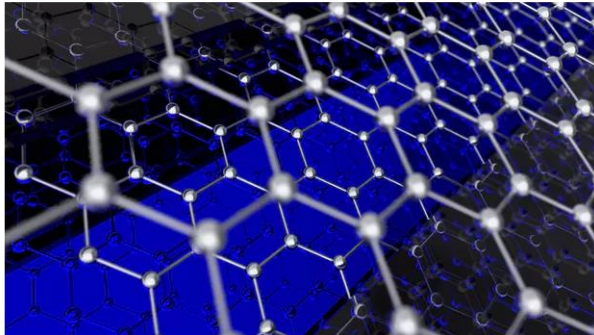
- Bipolar faces **power** and **size** limitation
- **CMOS logic gate**
 - 1963, *Wanlass*
- PMOSFET
 - 1970, *first practical MOS IC, Calculator*
- NMOSFET
 - 1970, *high-density storay(4K)*
 - 1972, *first microprocessor(4004)*
 - 1974, *8080 microprocessor*



Technology Evolution (cont.)

Ultra-low power graphene-based transistor could enable 100 GHz clock speeds

Michael Irving | May 24, 2016



Scientists at MIPT have developed a new type of power-efficient transistor using bilayered graphene.

Nanowire Transistors Could Let You Talk, Text, and Tweet Longer

Transistors with compound-semiconductor nanowires could consume less power than today's silicon FinFETs

By Richard Stevenson
Posted 26 Jan 2016 | 20:34 GMT

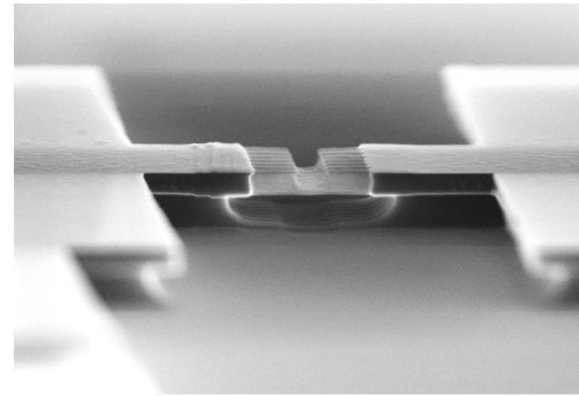


Image: Purdue University

Hybrid III-V/silicon SOA for photonic integrated circuits

Conference Paper (PDF Available) in Proceedings of SPIE - The International Society for Optical Engineering 9277-9277-6 · October 2014 with 239 Reads
DOI: 10.1117/12.2074617
Conference: Proc. SPIE, At Beijing, China, Volume: 9277

1st Peter Kaspar
il 24.57 · III-V Lab, Alcatel Lucent Bell Labs

2nd R. Brenot

3rd A. Le Liepvre

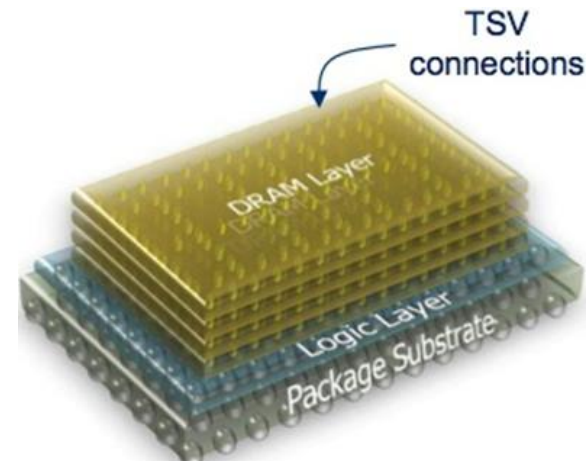


Last Sylvie Menezo
il 25.36 · Cea Leti

Show more authors

Abstract

Silicon photonics has reached a considerable level of maturity, and the complexity of photonic integrated circuits (PIC) is steadily increasing. As the number of components in a PIC grows, loss management becomes more and more important. Integrated semiconductor optical amplifiers (SOA) will be crucial components in future photonic systems for loss compensation. In addition, there are



Moore's Law

The experts look ahead

Cramming more components onto integrated circuits

With unit cost falling as the number of components per circuit rises, by 1975 economics may dictate squeezing as many as 65,000 components on a single silicon chip

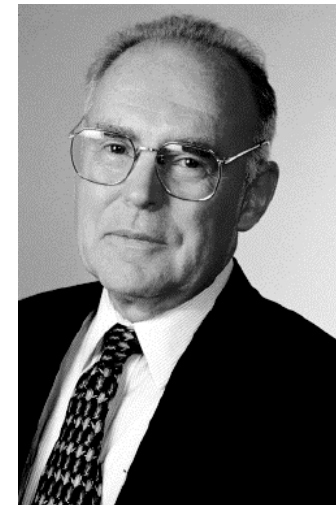
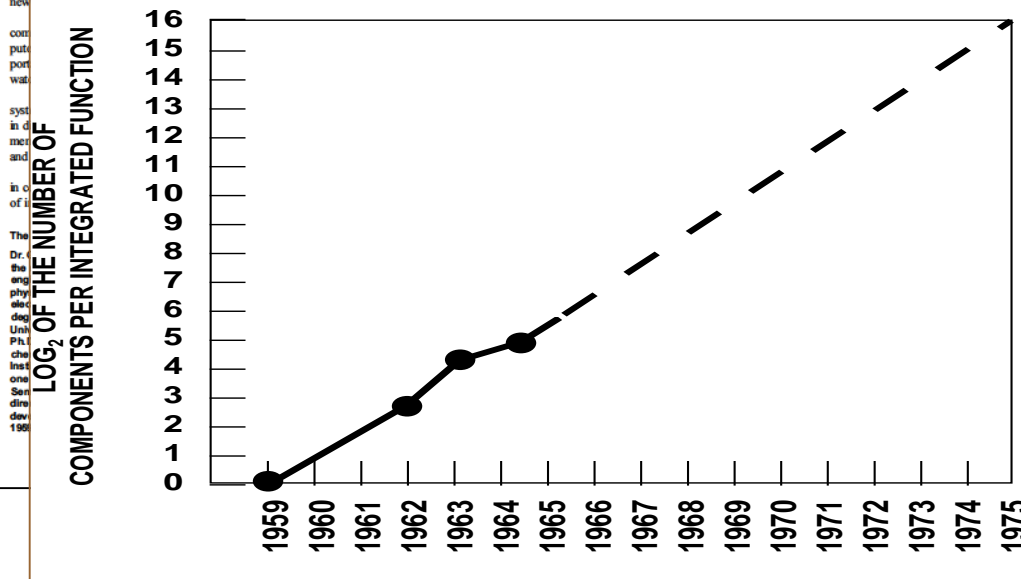
By Gordon E. Moore

Director, Research and Development Laboratories, Fairchild Semiconductor division of Fairchild Camera and Instrument Corp.

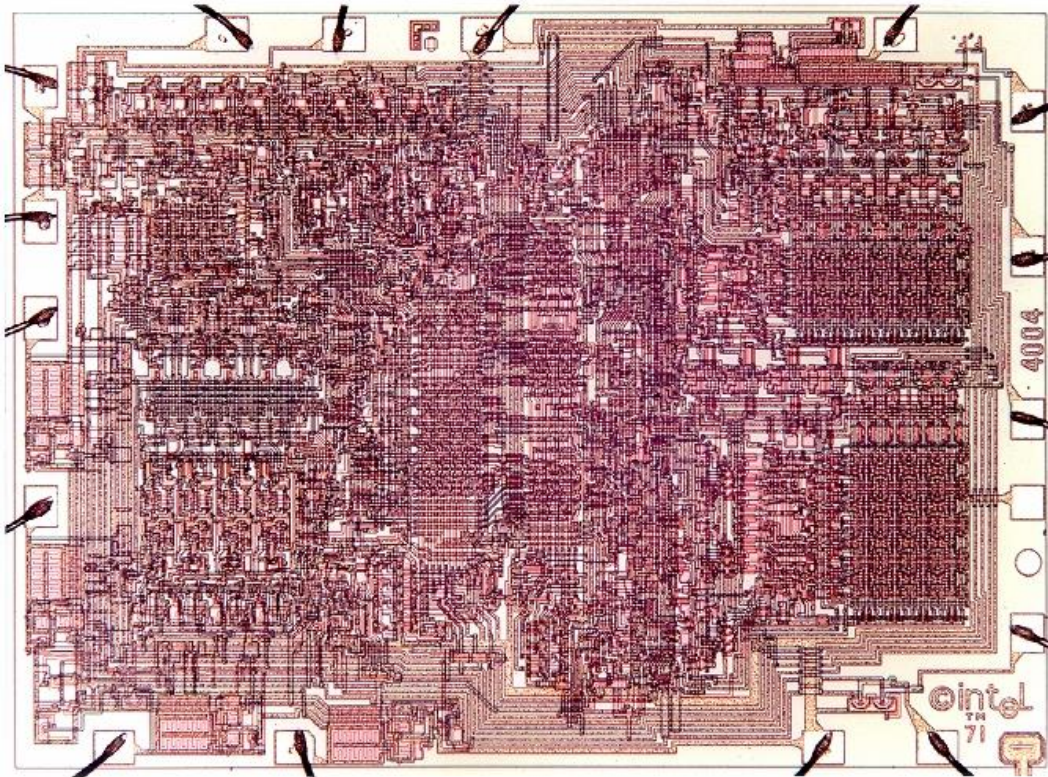
The future of integrated electronics is the future of electronics itself. The advantages of integration will bring about a proliferation of electronics, pushing this science into many new machines instead of being concentrated in a central unit. In addition, the improved reliability made possible by integrated circuits will allow the construction of larger processing units.

□ Electronics, Apr. 19, 1965

Gordon Moore (co-founder of Intel) made a prediction that semiconductor technology will double its effectiveness every 18 months



Intel 4004:1972

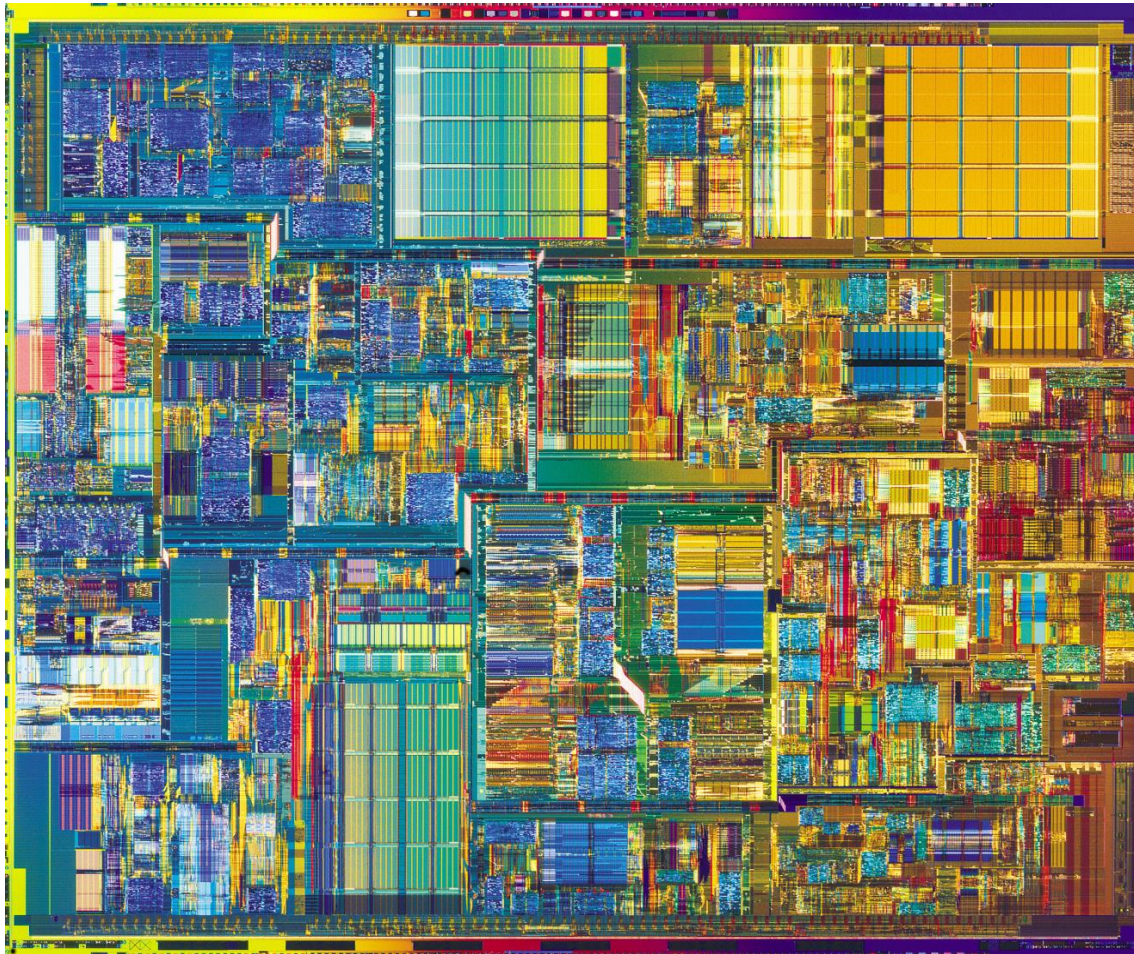


- First micro-processor on a single chip
- 2 300 transistors
- 0.3 mm x 0.4 mm
- 4 bit words
- Clock: 0.108 MHz

You will have the possibility to design a more powerful processor in one of our courses



Intel Pentium 4 (2000)

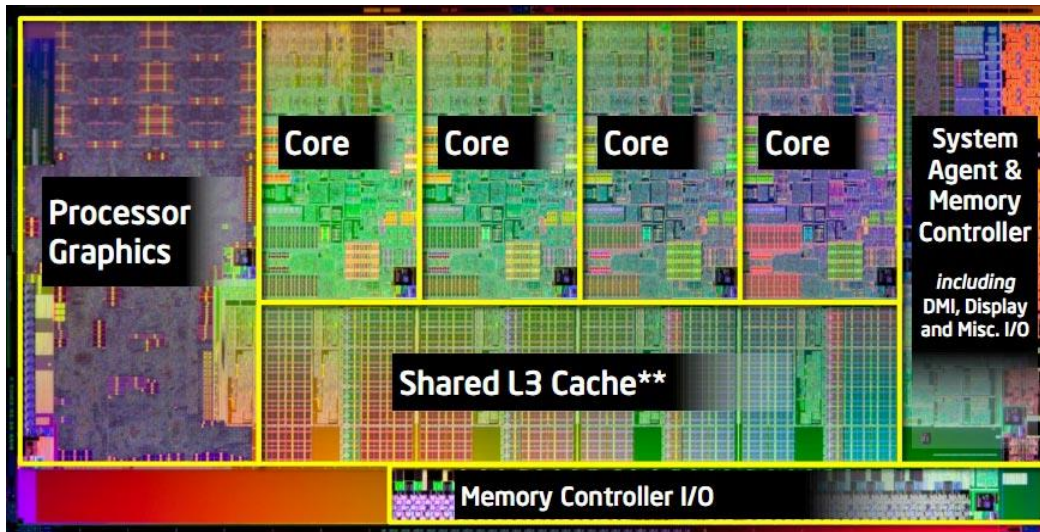


- ❑ 42 000 000 transistors
- ❑ 0.18 micron CMOS
- ❑ Clock: 1.5 GHz
- ❑ Die: 20 mm²

Baseband ASIC of a modern mobile phone has easily 10 times more transistors.

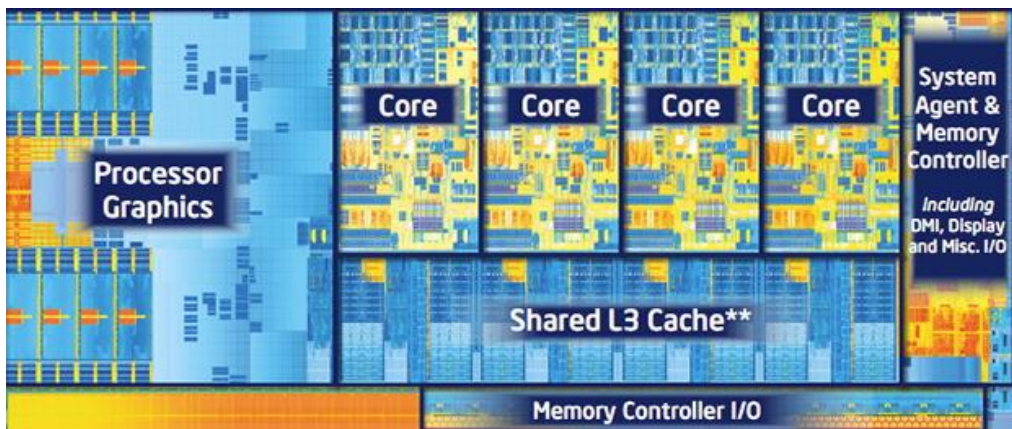


SandyBridge (2009)



- 32 nm-64 bit
- 995 000 000 Transistors (**23 × P4**)
- ~**3.5 GHz**
- 216 mm²

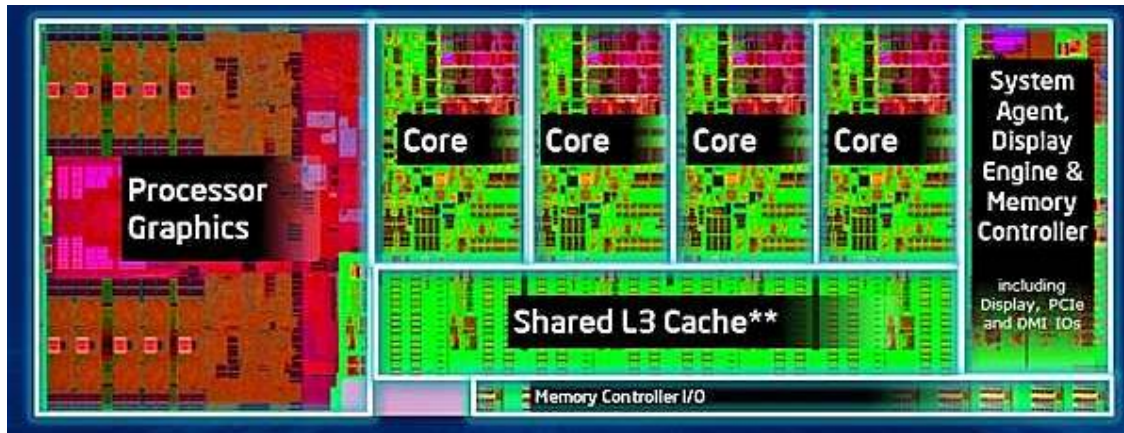
IvyBridge (2011)



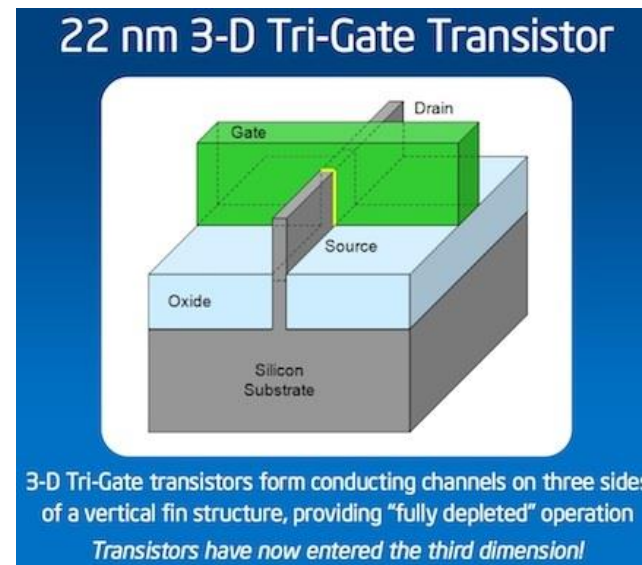
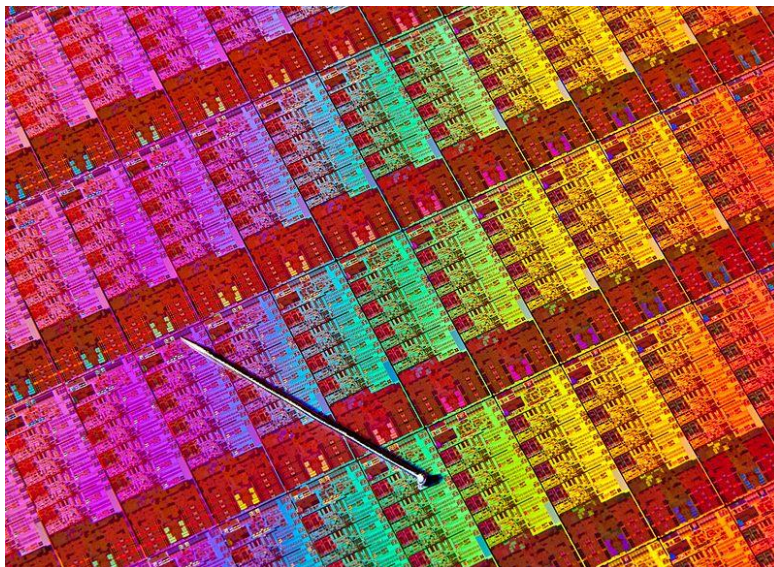
- 22 nm-64 bit
- 1.4b Transistors
- ~**3.5 GHz**
- 160 mm²



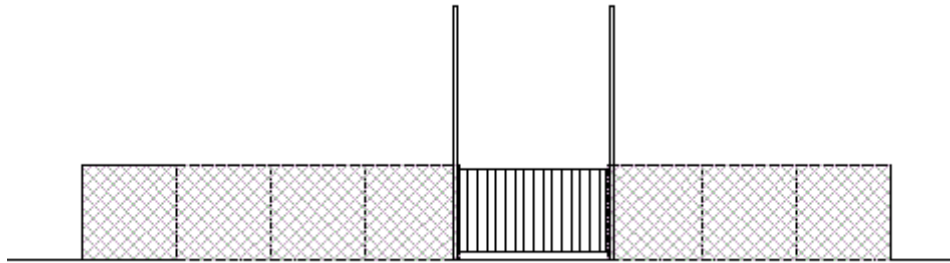
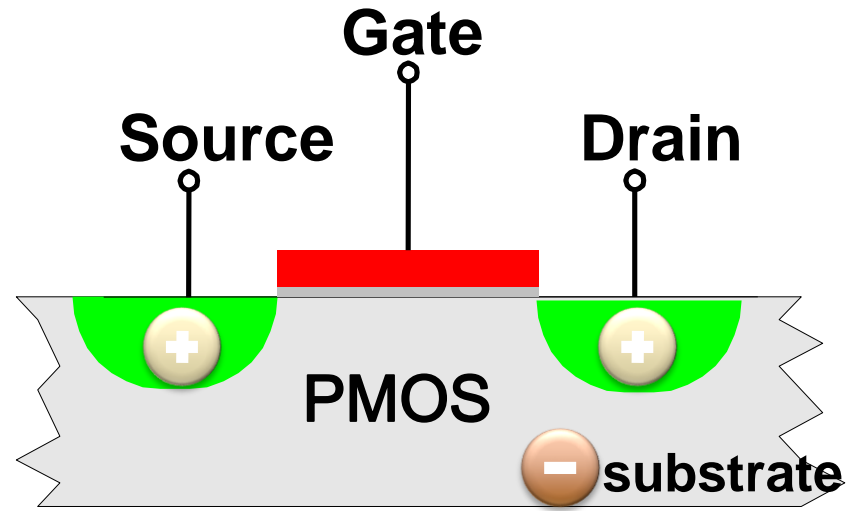
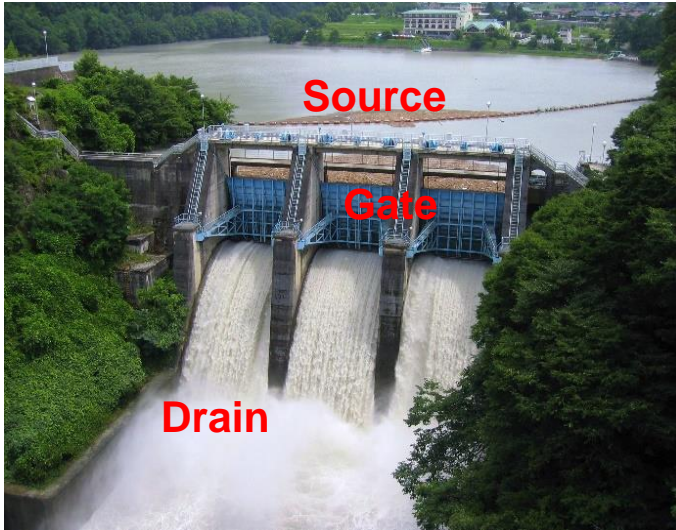
Haswell (2013)



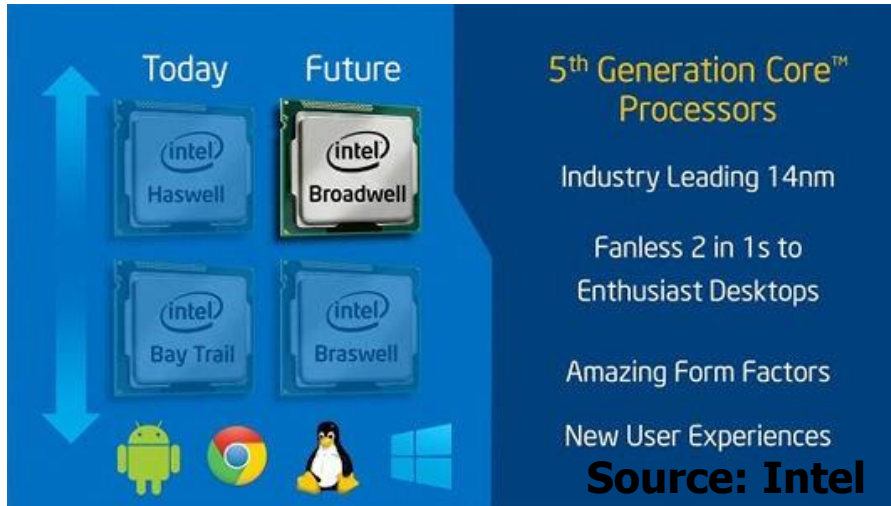
- 22 nm
- **Tri-gate 3D transistor**
- **1.4b Transistors**
- **~3.5 GHz**
- **177 mm²**



FinFET



Braswell (2014)



The diagram shows four Intel processors arranged in a 2x2 grid. The top row is labeled 'Today' and contains Haswell and Broadwell. The bottom row is labeled 'Future' and contains Bay Trail and Braswell. A blue double-headed arrow is on the left. To the right, text describes the 5th Generation Core™ Processors as 'Industry Leading 14nm', 'Fanless 2 in 1s to Enthusiast Desktops', and 'Amazing Form Factors'. It also mentions 'New User Experiences' and lists OS icons: Android, Chrome, Linux, and Windows.

Today Future

intel Haswell intel Broadwell

intel Bay Trail intel Braswell

5th Generation Core™ Processors

Industry Leading 14nm

Fanless 2 in 1s to Enthusiast Desktops

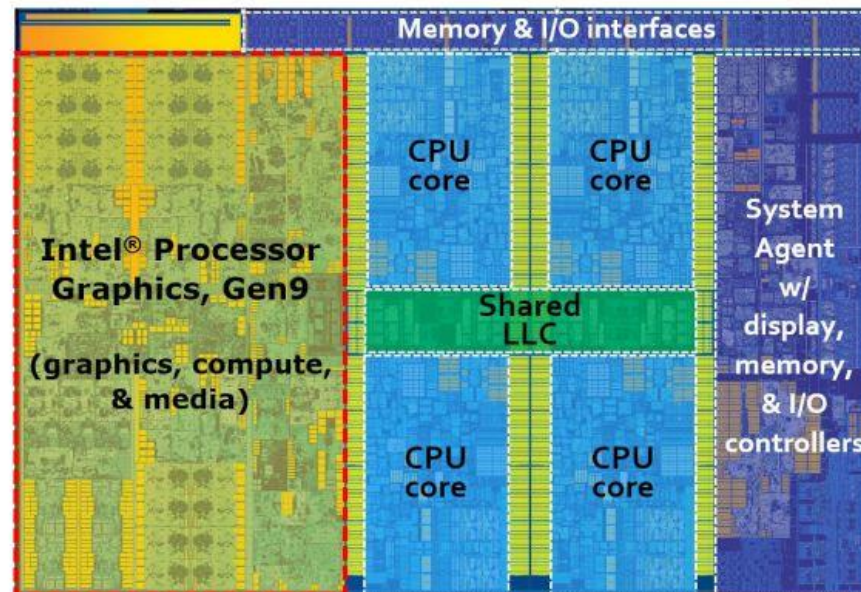
Amazing Form Factors

New User Experiences

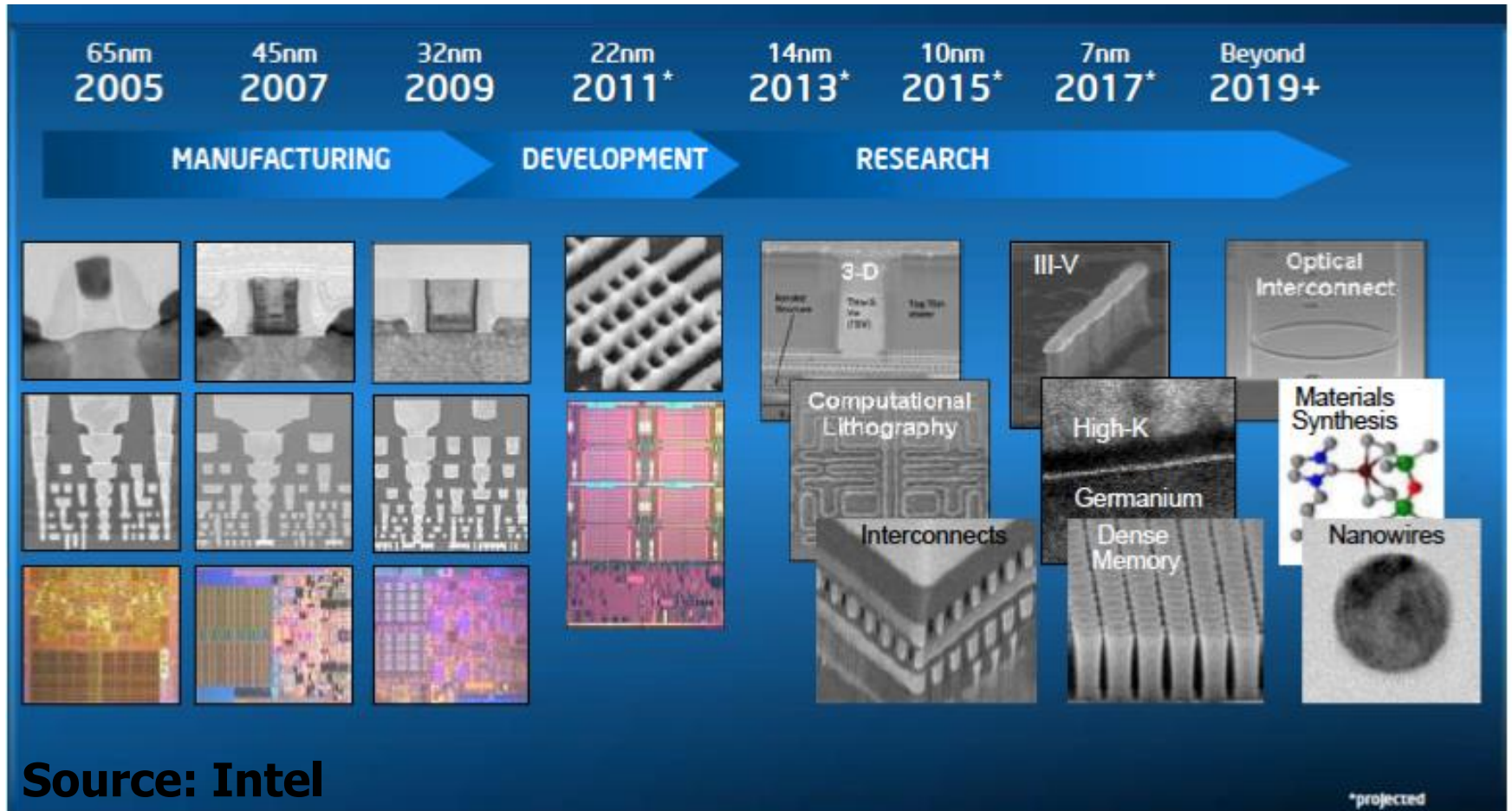
Source: Intel

Skylake (2015)

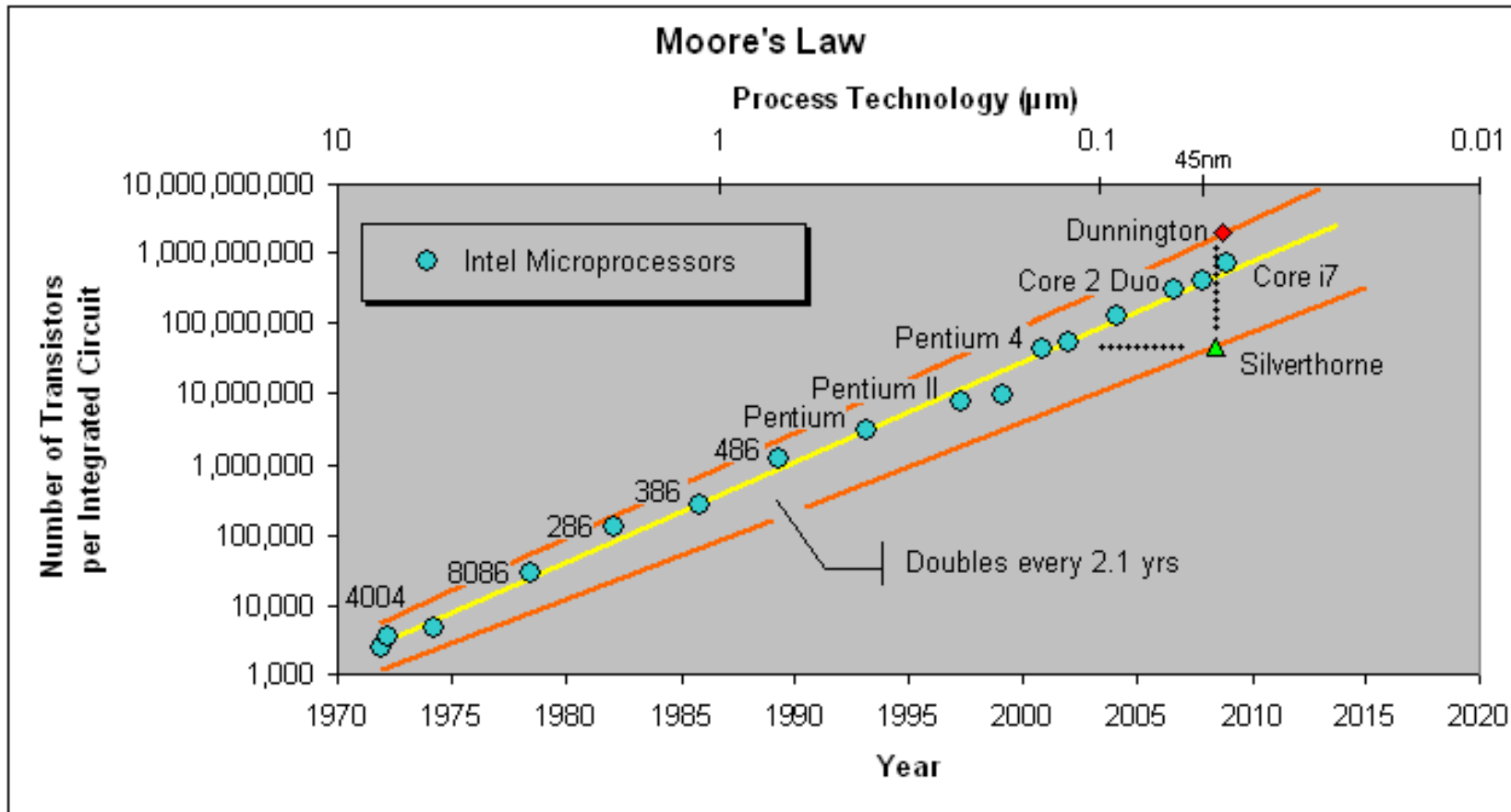
- ❑ 14 nm
- ❑ Tri-gate 3D transistor (FinFET)
- ❑ 1.4b Transistors
- ❑ ~4 GHz
- ❑ 8MB Cache



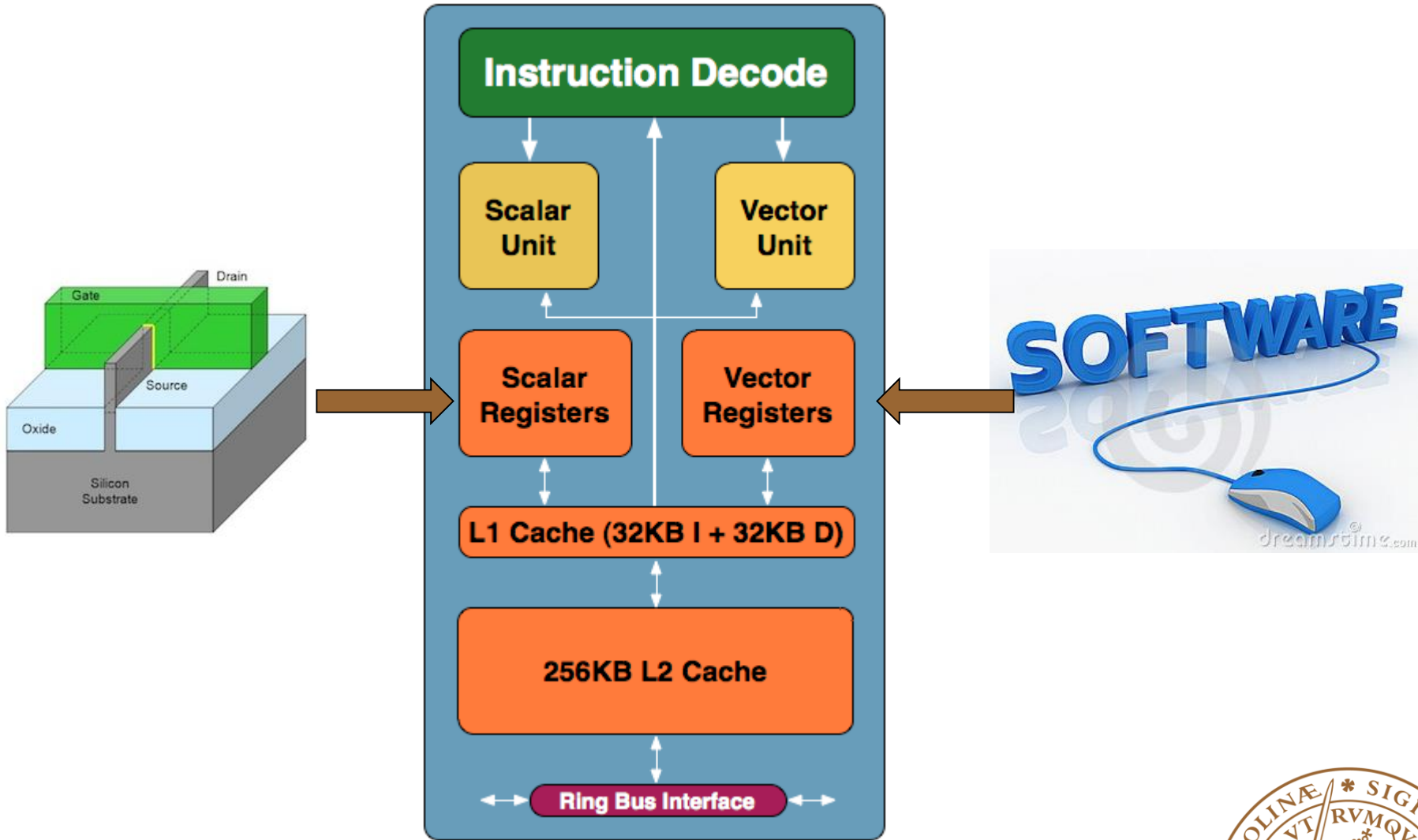
On-Time 2 Year Cycles



Moore's Law: number of transistors



Intel Architecture

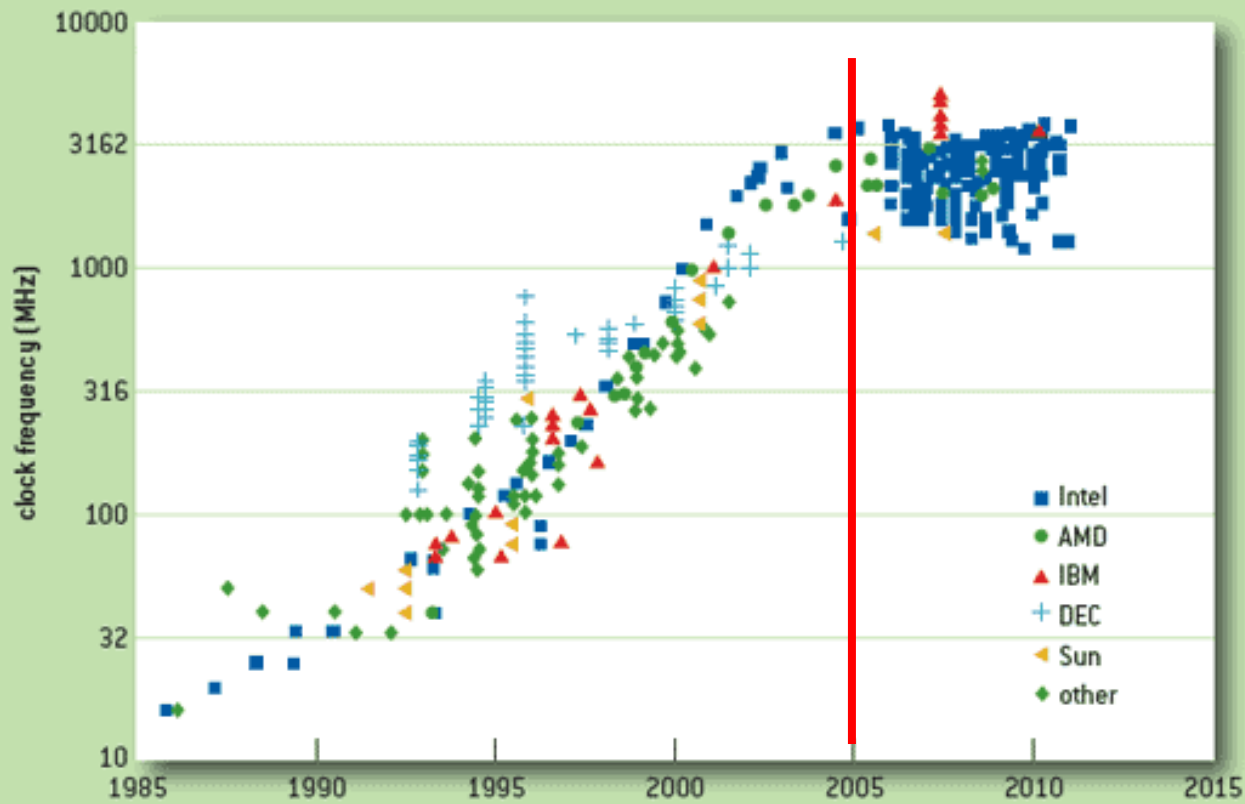


Moore's Law: frequency

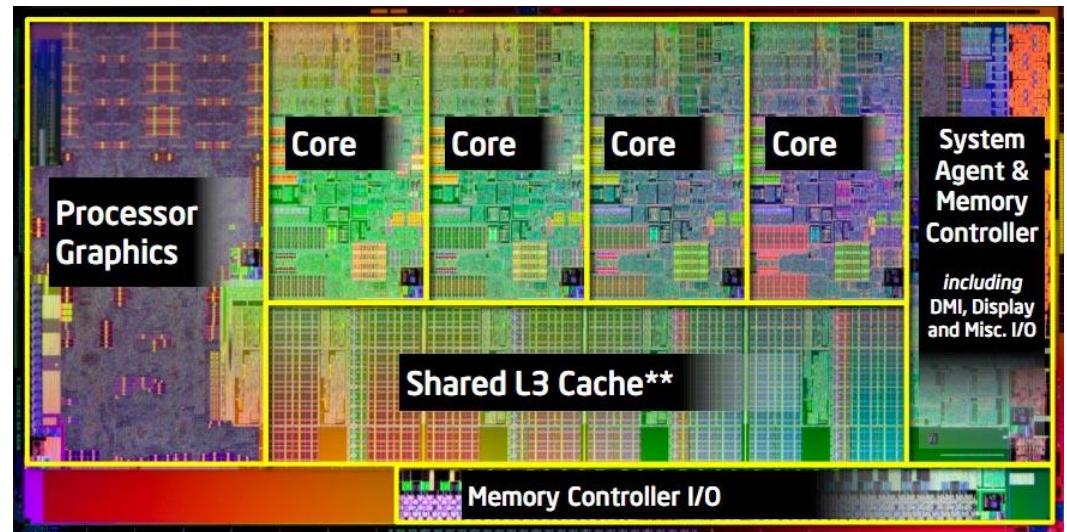
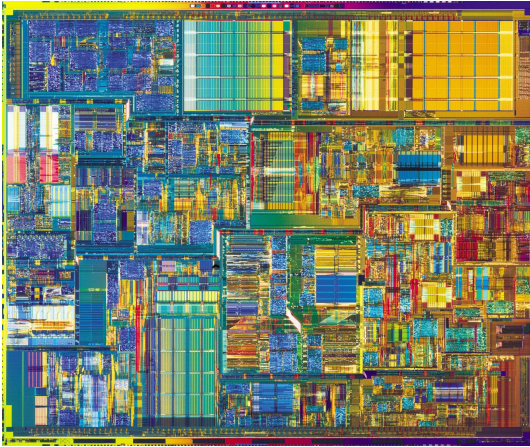
FIGURE 7

Source: CPU DB: Recording Microprocessor History

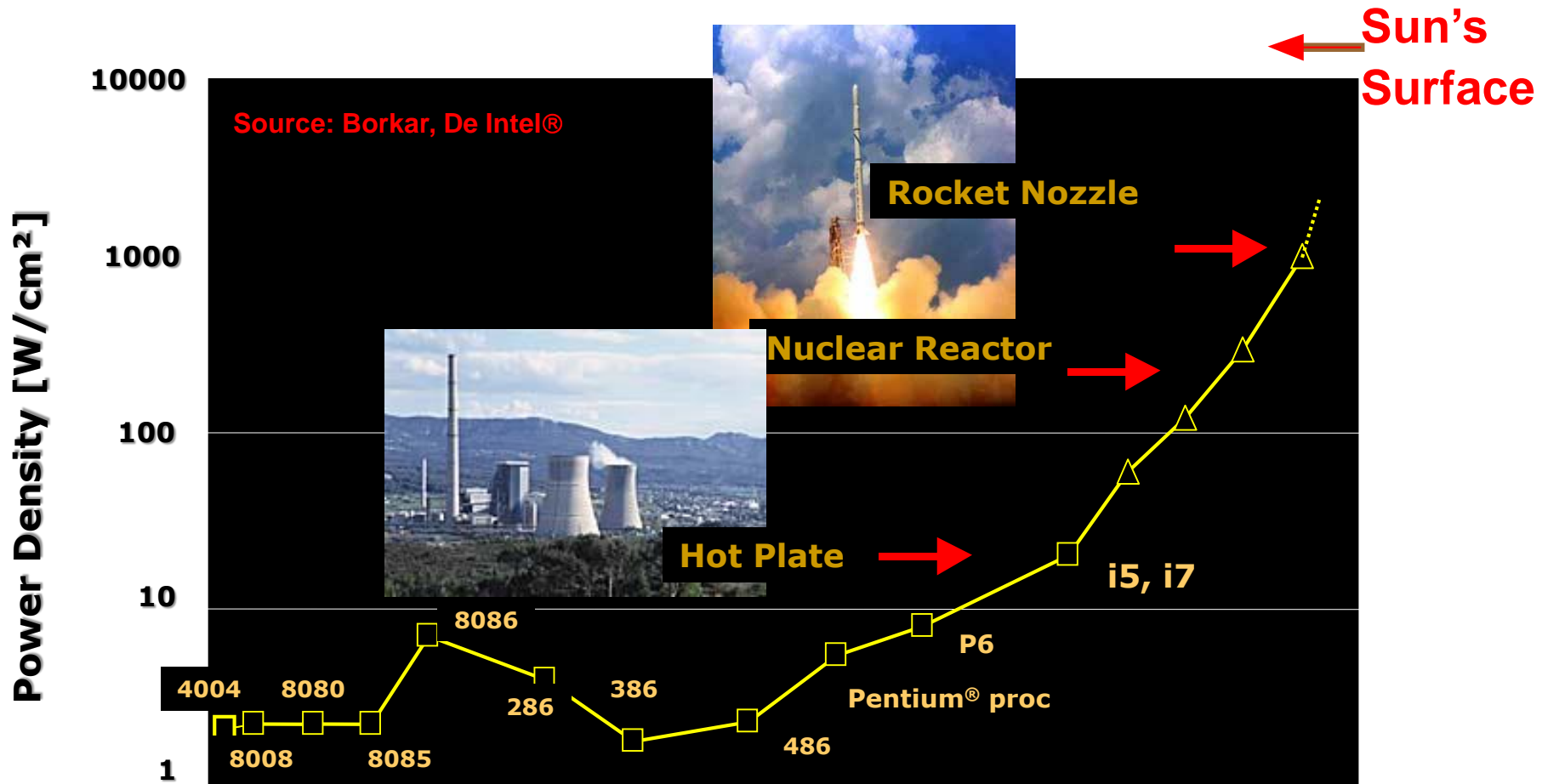
Processor Frequency Scaling Over Time



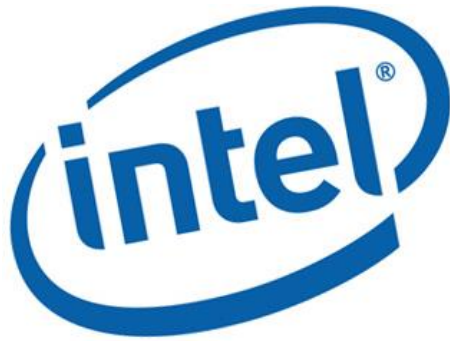
Architecture change due to physical limitation



Moore's Law: power density



Architecture change due to new applications



ARM



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- Advantages
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□ History & Roadmap

□ Device Technology & Platforms

□ System Representation

□ Design Flow

□ RTL Basics



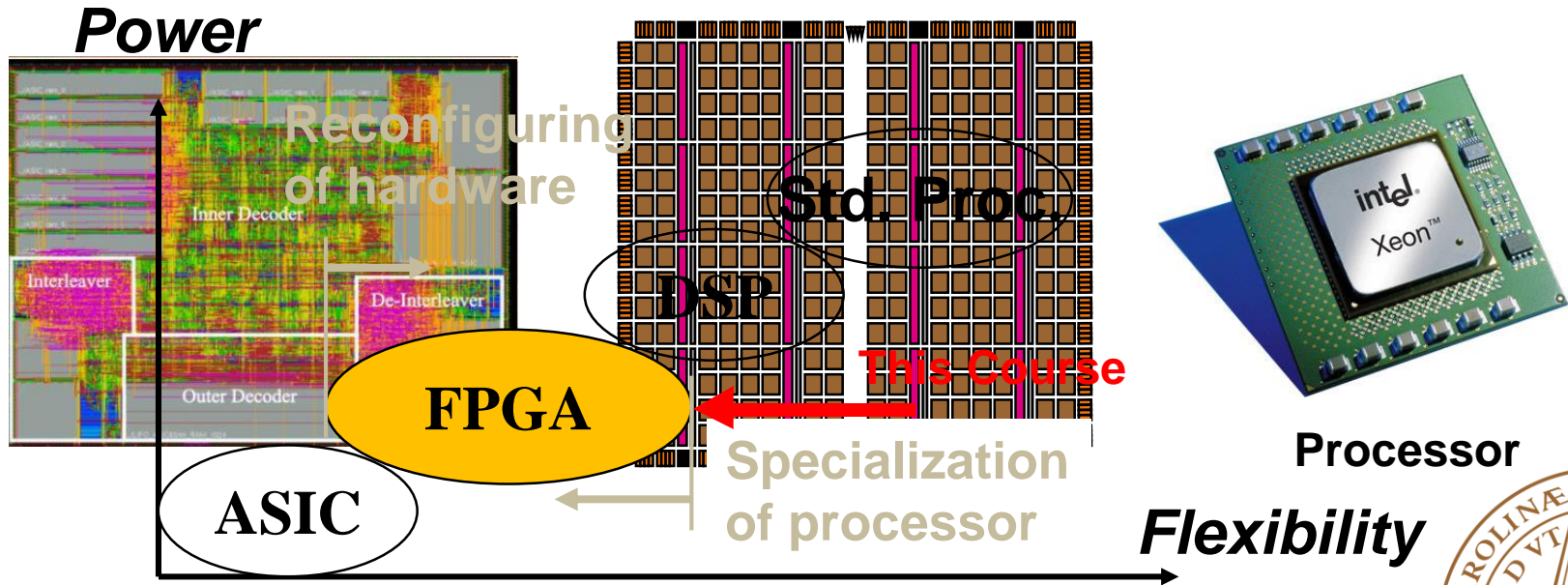
Devices

□ General-purpose integrated circuits

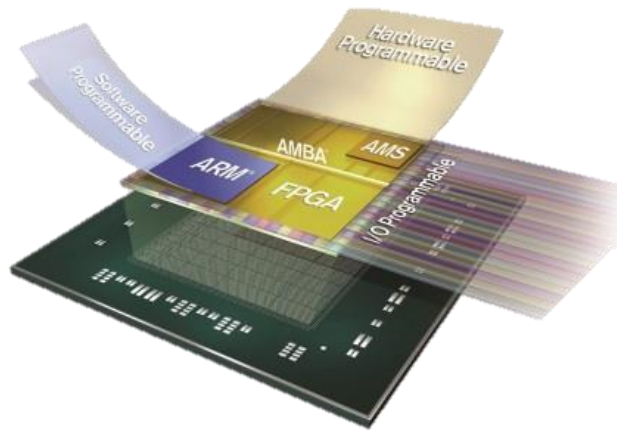
- **Microprocessors**, digital signal processors, **FPGA** and memories

□ Application-specific integrated circuits (ASIC)

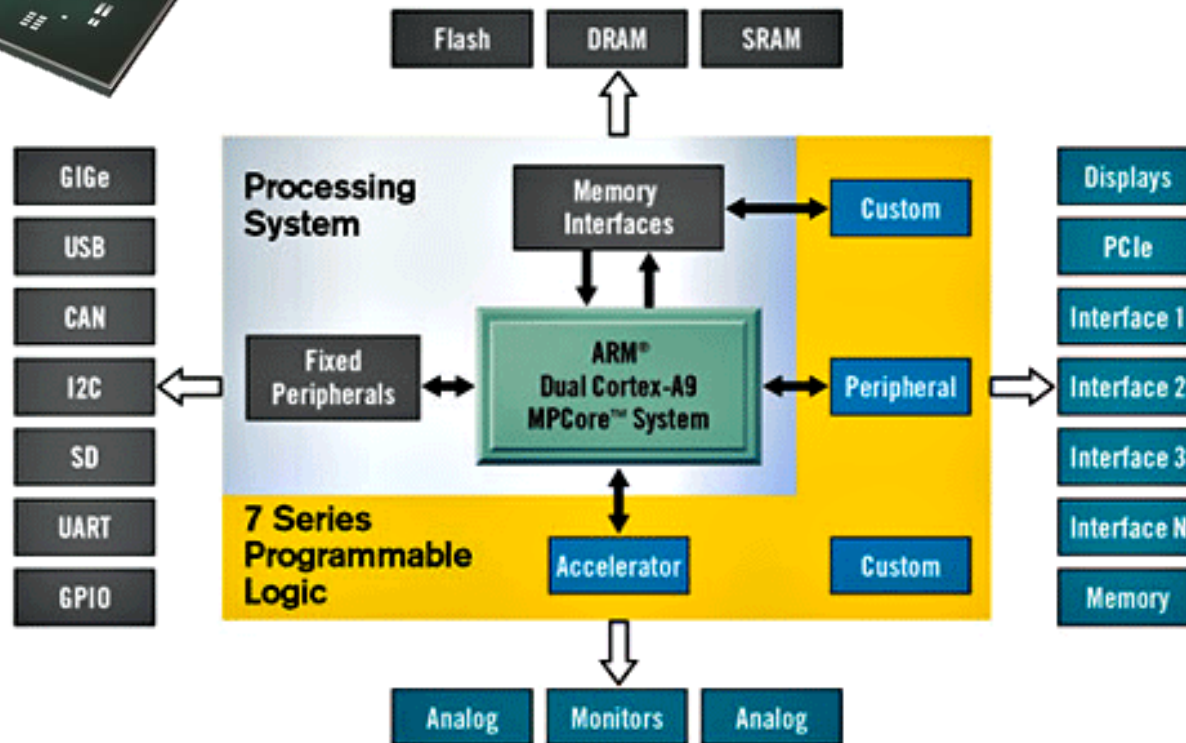
- Designed for a narrow range of applications
- Full-custom ASIC
- **Standard-cell ASIC**



Devices (heterogeneous)



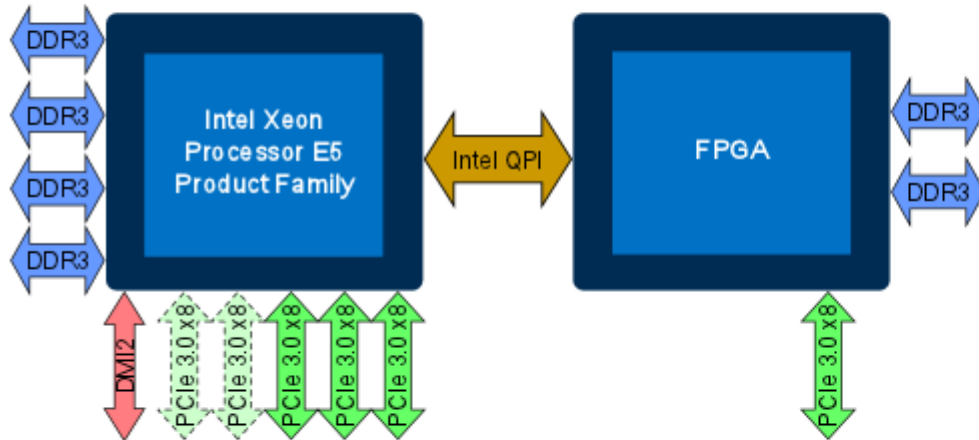
All Programmable SoC



Devices

Intel® Xeon® Processor + Field Programmable Gate Array Software Development Platform (SDP) Shipping Today

Software Development for Accelerating Workloads using Intel® Xeon® processors and coherently attached FPGA in-socket



Processor	Intel® Xeon® Processor E5
FPGA Module	Altera® Stratix™ V
QPI Speed	6.4 GT/s full width (target 8.0 GT/s at full width)
Memory to FPGA Module	2 channels of DDR3 (up to 64 GB)
Expansion connector to FPGA Module	PCI Express™ (PCIe) 3.0 x8 lanes - maybe used for direct I/O e.g. Ethernet
Features	Configuration Agent, Caching Agent, (optional) Memory Controller
Software	Accelerator Abstraction Layer (AAL) runtime, drivers, sample

Available as part of Intel & Altera co-sponsored Hardware Accelerator Research Program

IDF15
INTEL DEVELOPER FORUM



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System Representation

□ System

- SoC: a CPU chip ...

□ Module

- Macro cell in a chip: ALU...

□ Gate

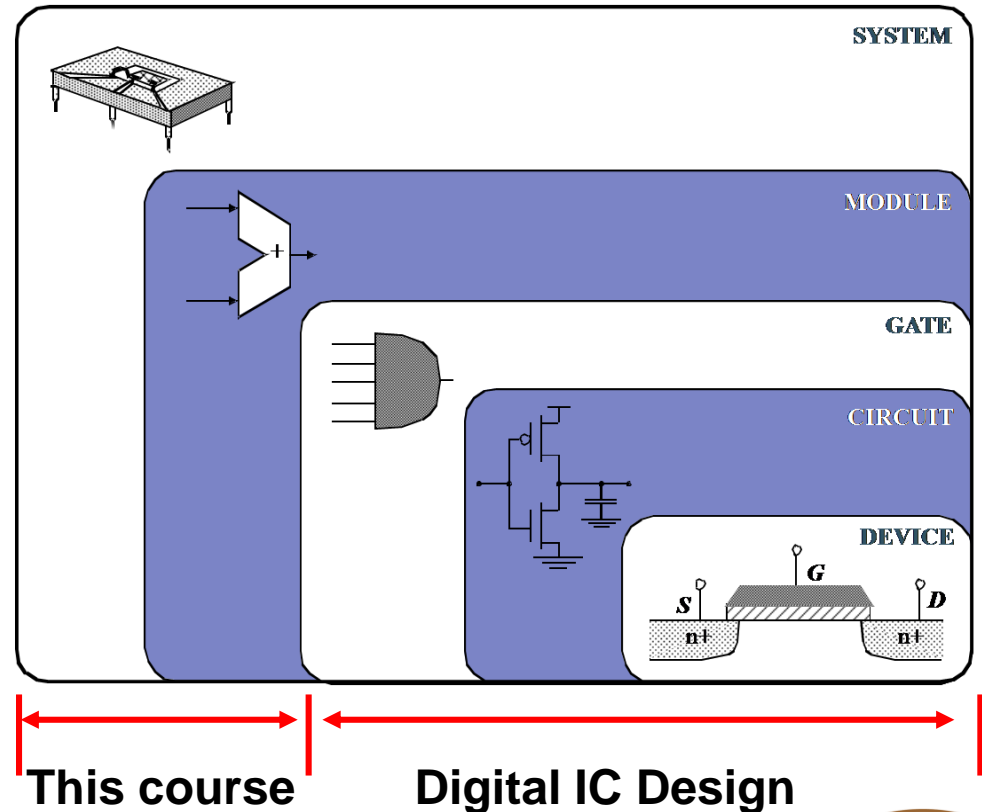
- Basic logic block: xor, nor...

□ Circuit

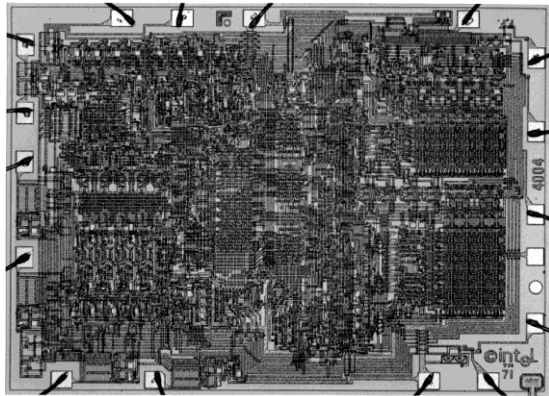
- Transistors

□ Device

- Gate, source, drain

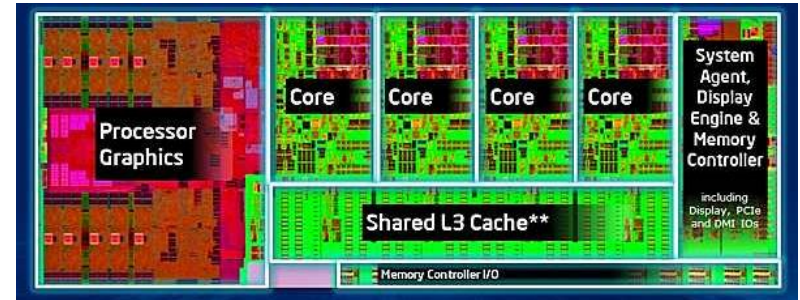


View a Design in a Proper Way



Intel 4004 (2.3K transistors)

Full-custom

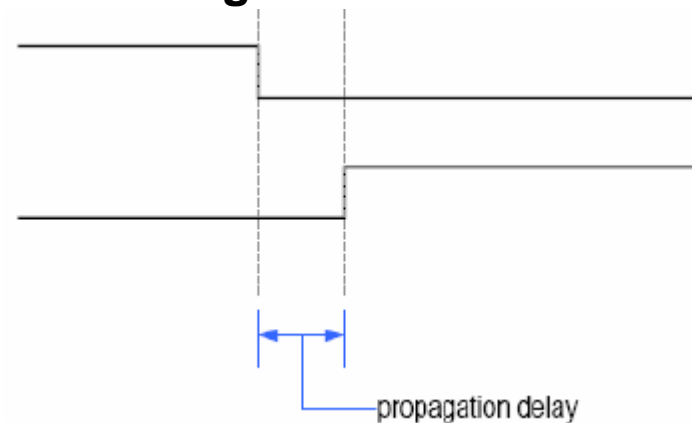
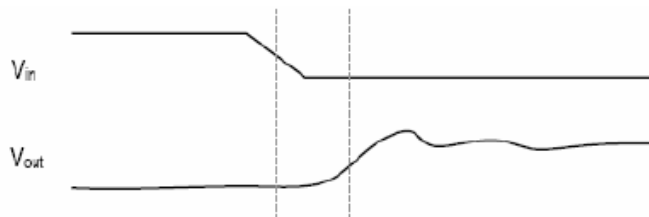


Intel Haswell (1.4B transistors)

?

□ Abstraction: simplified model of a system

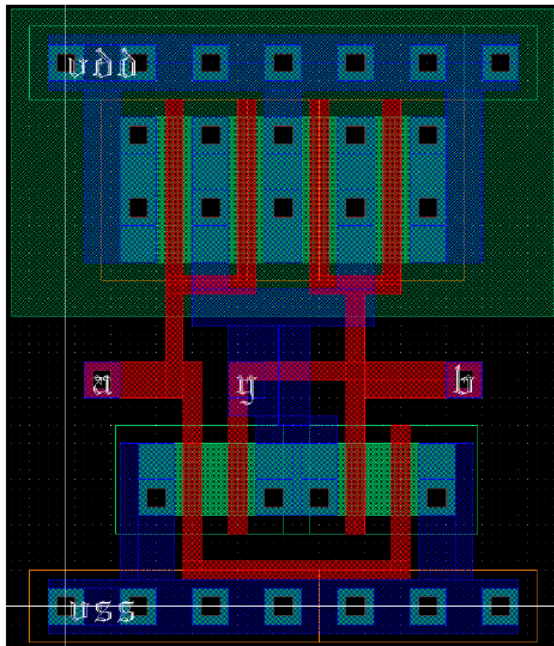
- Show the selected features accurate enough
- Ignore the others



VLSI Design Flow

□ Evolution of circuit design (Design Hierarchy)

- Full-custom \Rightarrow Design-automation
 - *Based on library cells and IPs*
 - *Top-down methodology*
- Design abstraction \Rightarrow “Black box” or “Model”
 - *Parameter simplification*
 - *Accurate enough to meet the requirement*



```
module HS65_GH_NAND2AX14 (Z, A, B);  
    output Z;  
    input A,B;  
    not U1 (INTERNAL1, B) ;  
    or #1 U2 (Z, A, INTERNAL1) ;  
    specify  
        (A +=> Z) = (0.1,0.1);  
        (B -=> Z) = (0.1,0.1);  
    endspecify  
endmodule // HS65_GH_NAND2AX14
```



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□ Design Flow

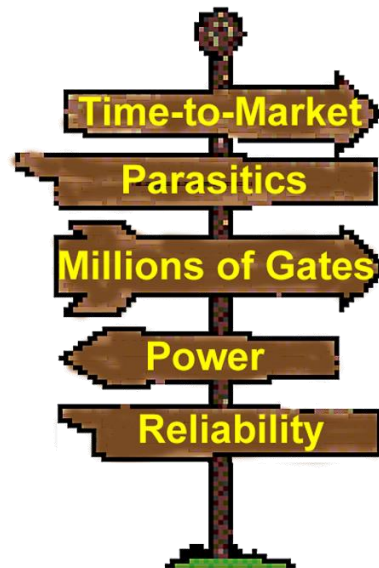
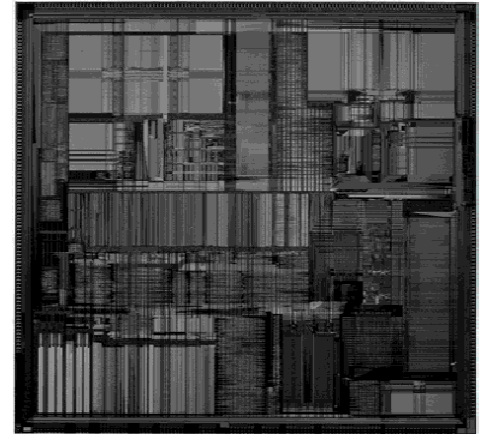
□ RTL Basics



VLSI Design

□ Set of specification:

- What does the chip **do**?
- How **fast** does it run?
- How **reliable** will it be?
- How is the silicon **area**?
- How much **power** will it consume?
-

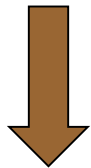


VLSI Design Flow

- An iterative process that transfer the specification to a manufacturable chip through at least five levels of design abstraction.

Specification

Function, performance, definition:
English

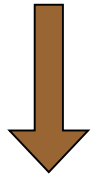


Behavior Design

Behavior, algorithm: C/C++, SystemC,
Matlab ...

Behavior simulation

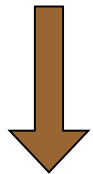
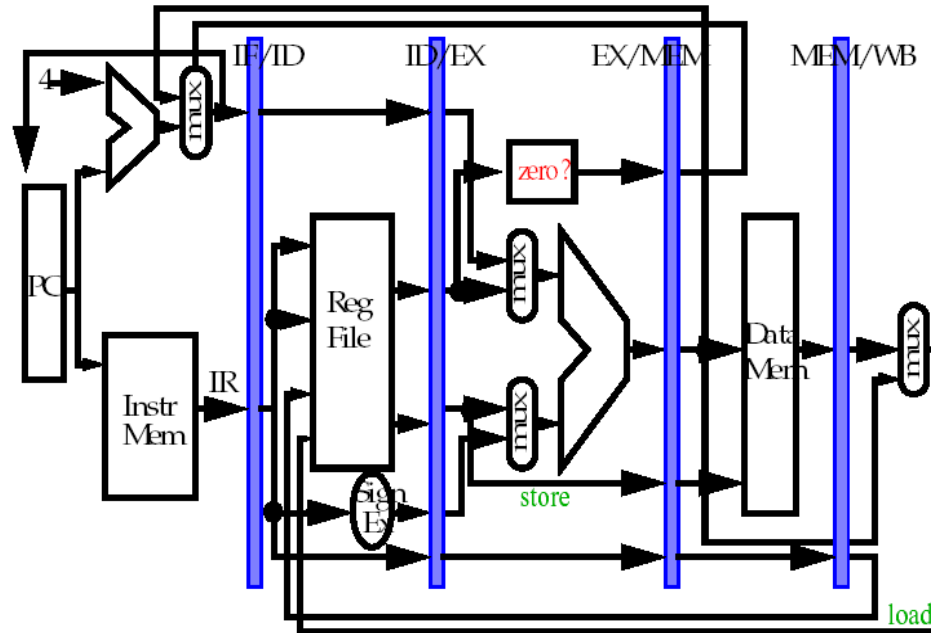




VHDL
Verilog

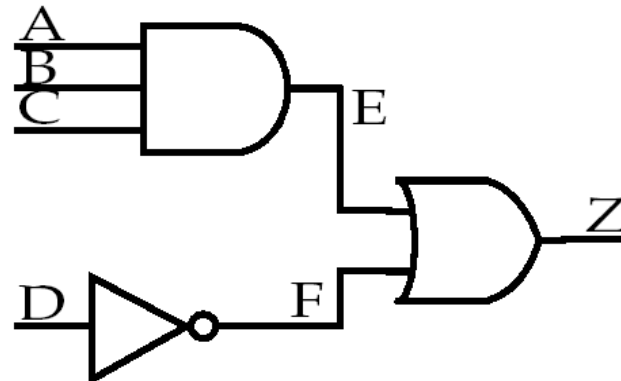
Register Transfer
Level Design

RTL simulation



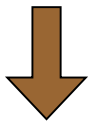
Synthesis

Logic Design



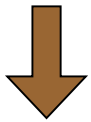
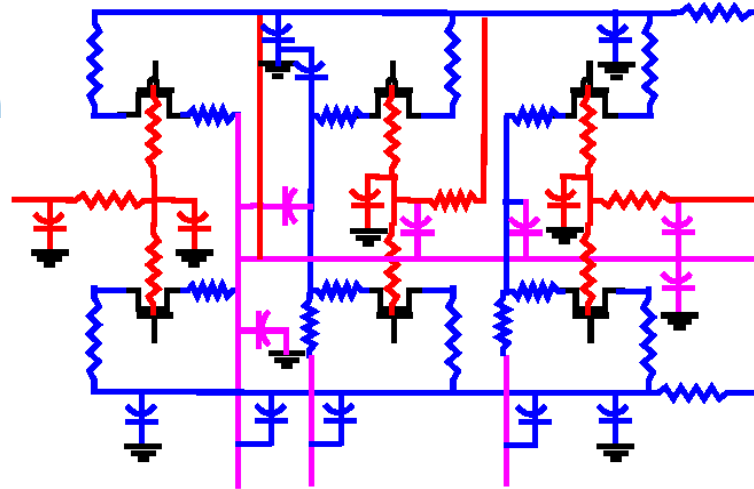
Gate-level simulation
Timing analysis
Power analysis





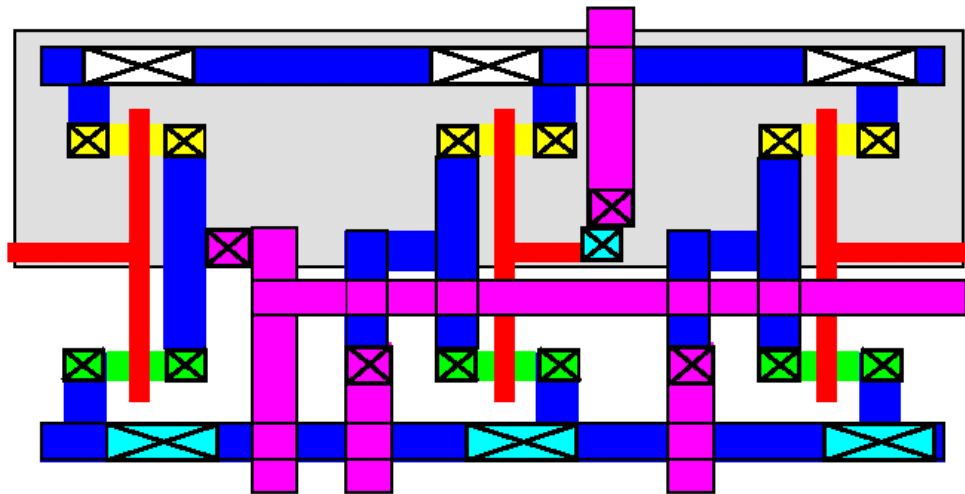
Custom Design

Circuit Design



Layout

Physical Design



Design rule checking
Post layout simulation



Verification

□ Verification

- Check whether a design meets the **specification** and **performance goals**

□ Two aspects

- **Functionality**
- **Performance (timing/power/area)**

□ Method of Verification

- **Simulation**
 - *Spot check: cannot verify the absence of errors*
 - *Can be computation intensive*
- **Timing analysis**
 - *Just check delay*
- Formal verification
 - *Apply formal math techniques determine its property*
 - *E.g, equivalence checking*
- **Hardware emulation**



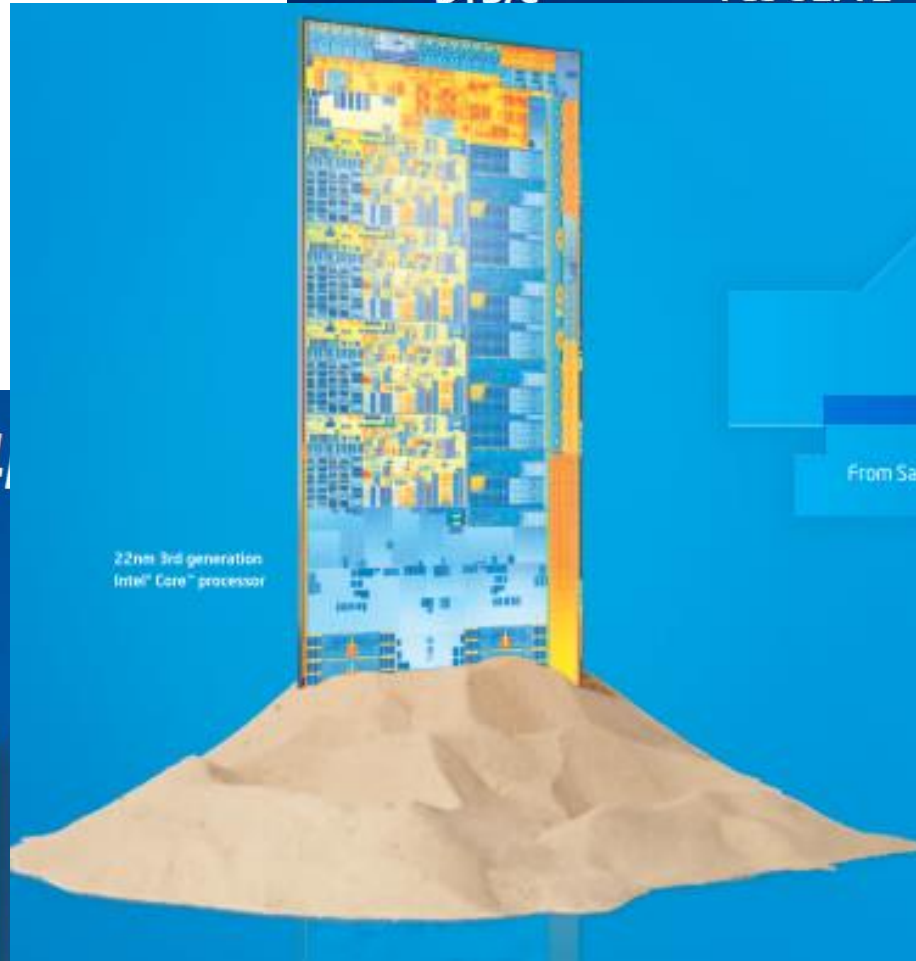
Fabrication

22nm Fab Upgrades

D1D/C

Fab 32/12

Fab 28
Israel



From Sand

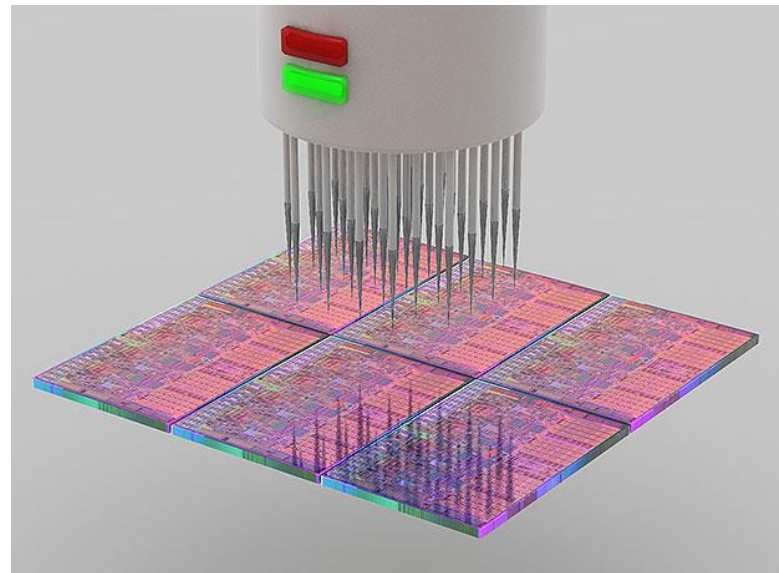
14

D1X
Oregon



Testing

- Testing is the process of detecting physical defects of a die or a package occurred at the time of manufacturing
- **Testing** and **verification** are different tasks.
- **Difficult for large circuit**
 - Need to add auxiliary testing circuit in design
 - E.g., built-in self test (BIST), scan chain etc.



VLSI Design Flow: Tools

□ Algorithm

- **Matlab**

□ RTL Simulation

- **Modelsim, Mentor**
- VCS, Synopsys
- VerilogXL, Cadence

□ Logic Synthesis

- **Design Compiler, Synopsys**
- Blast Create, Magma

□ Transistor Simulation

- **Hspice/Starsim, Synopsys**
- Spectra, Cadence
- Eldo, Mentor

□ Mixed-Signal Simulation

- **AMS Designer, Cadence**
- ADMS, Mentor
- Saber, Synopsys

□ Place & Route

- Astro, Synopsys
- **Silicon Encounter, Cadence**
- Blast Fusion, Magma

□ Layout

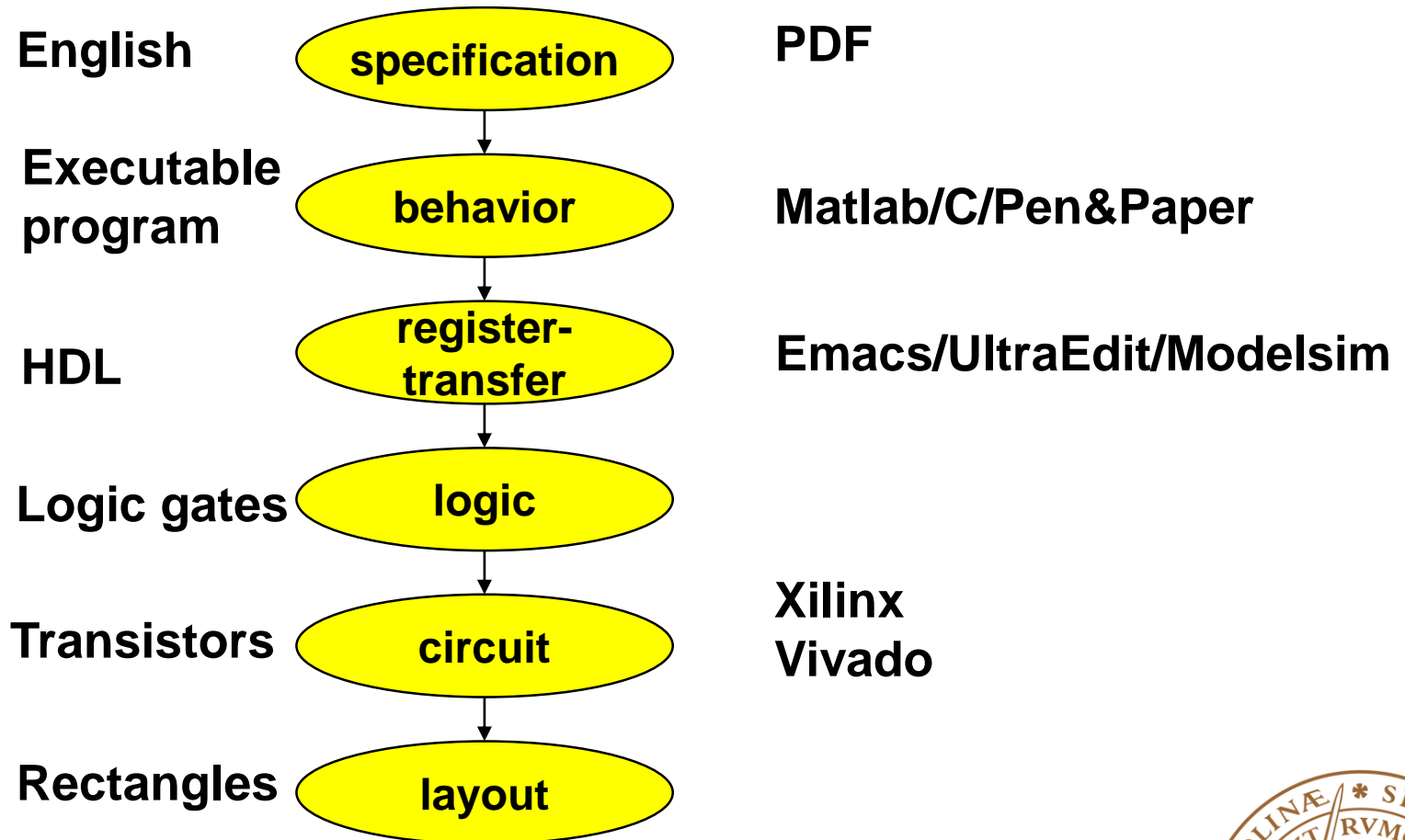
- **Icfb/Dracula, Cadence**
- ICstation/Calibre, Mentor

□ FPGA

- **Vivado, Xilinx**
- Quatus, Altera



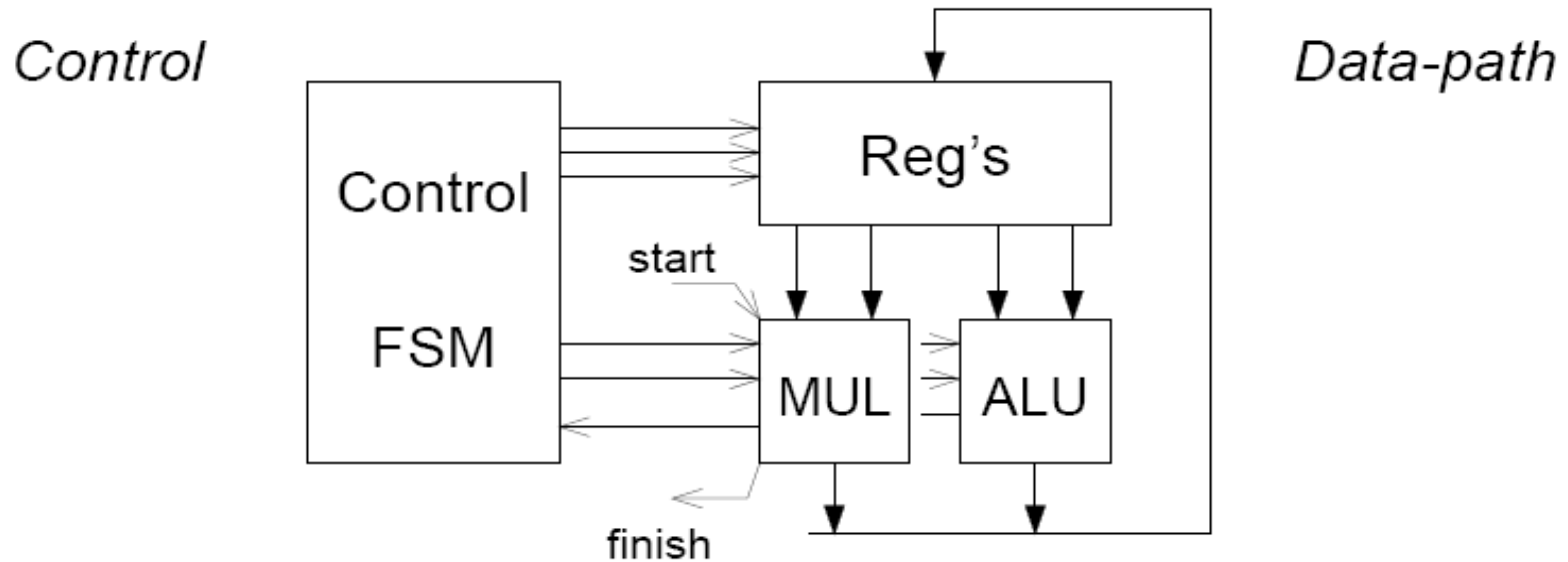
VLSI Design Flow: Summary



Following slides should fresh up your memory



Overall VLSI Structure



□ Scheduling / ordering / sequencing of operations

□ Mapping / allocation:

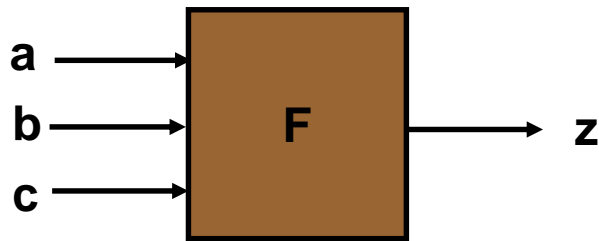
- Variables -> {Reg1, ... ,RegN}
- Operations -> {MUL, ADD, ALU, ... ,}

We will implement something similar in this course



Two Basic Digital Components (What)

Combinational Logic

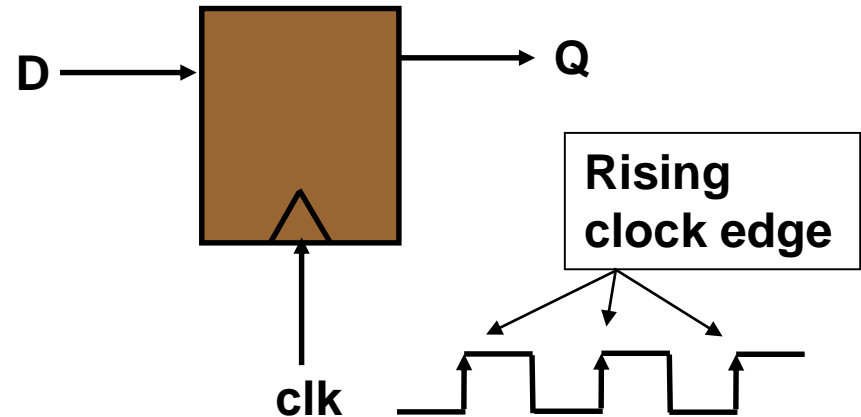


Always:

```
z <= F(a, b, c);
```

i.e. a function that is always evaluated when an input changes.
Can be expressed by a truth table.

Register



```
if clk' event and clk= '1' then  
  Q <= D;
```

i.e. a stored variable,
Edge triggered D Flip-Flop
with enable.



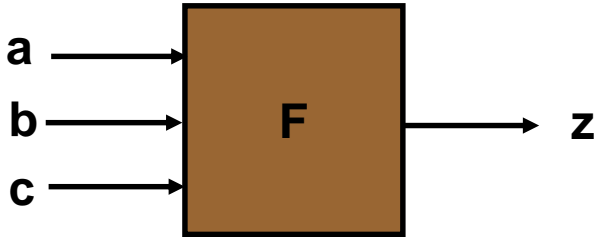
Timing (When)

Only if we guarantee to meet the **timing requirements**

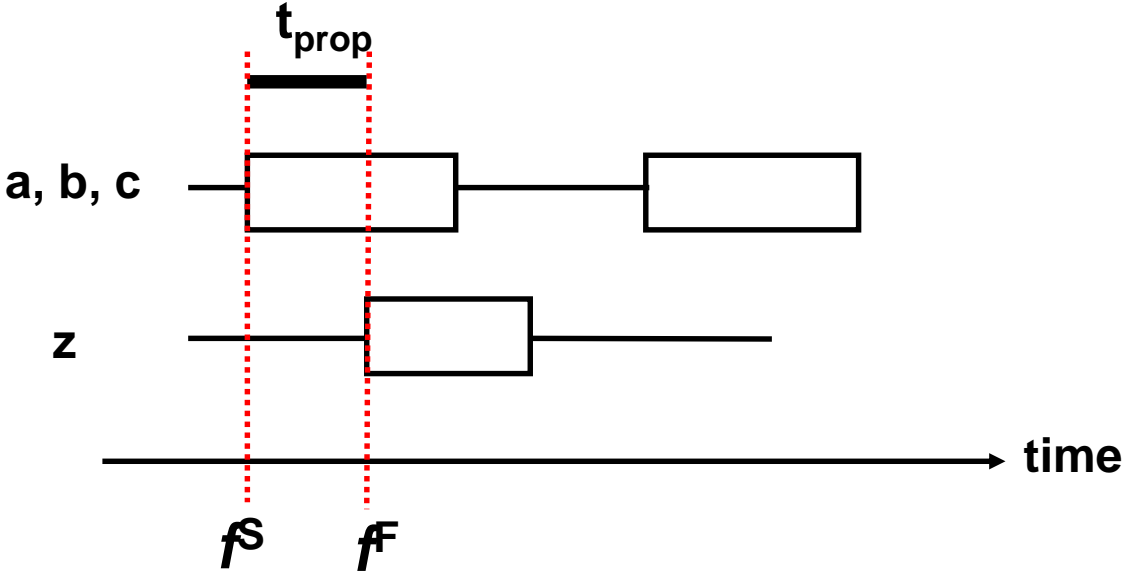
... do the components guarantee to behave as intended.



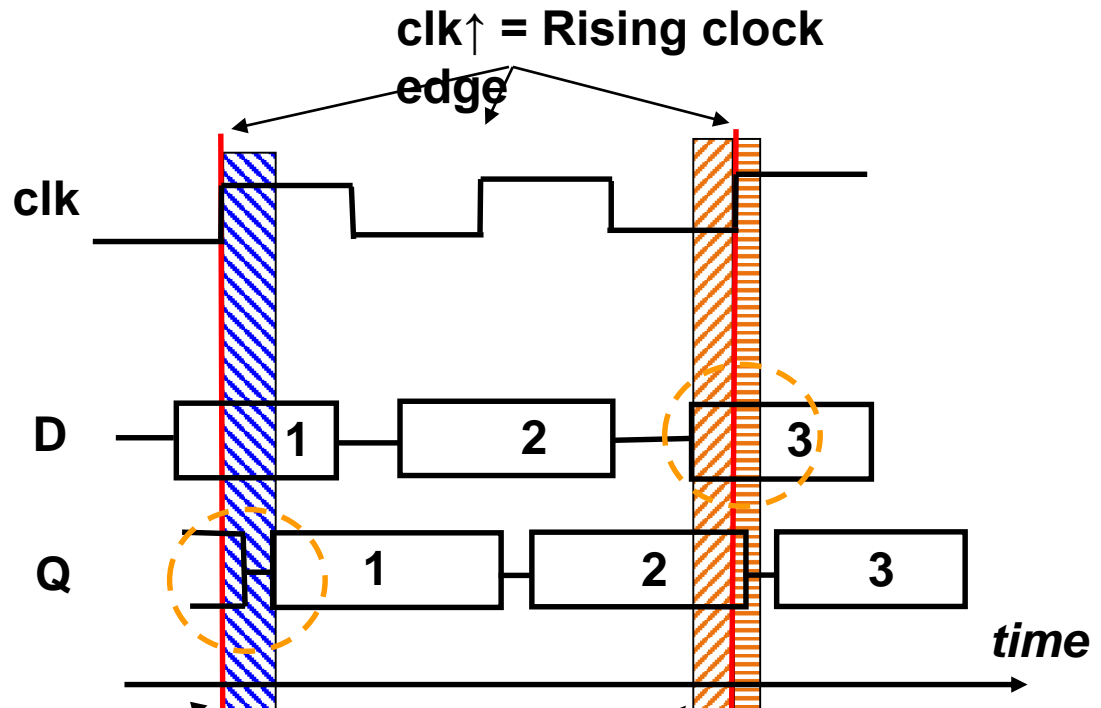
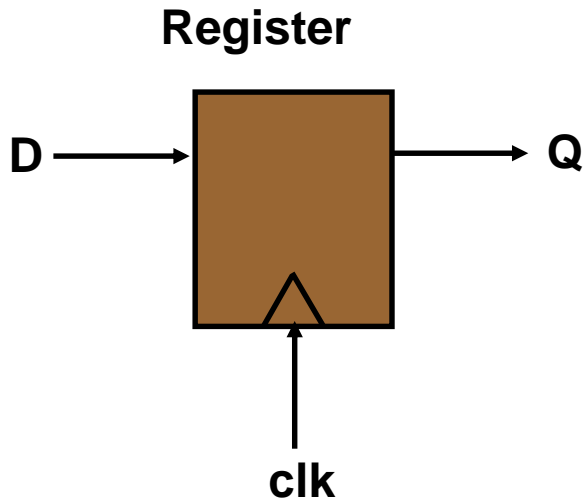
Combinational Logic Timing



- **Propagation delay:**
After presenting new inputs
Worst case delay before
producing correct output



Register timing



Propagation delay (clk_to_Q):
Worst case (maximum) delay after $\text{clk}\uparrow$ before new output data is valid on Q.

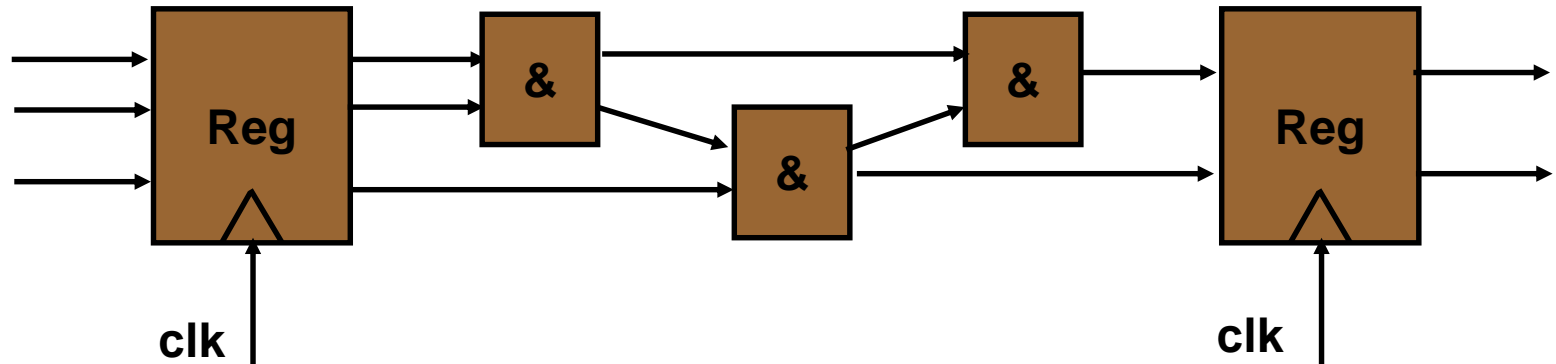
Setup time: Minimum time input must be stable before $\text{clk}\uparrow$

Hold time: Minimum time input must be stable after $\text{clk}\uparrow$



Clock Frequency (RTL)

□ What is the maximum clock frequency?



Register

Propagation delay:	T _{clk-Q}	250ps
Setup time:	T _{su}	200ps
Hold time:	T _h	100ps

AND-gate

Propagation delay:	T _{prop}	250ps
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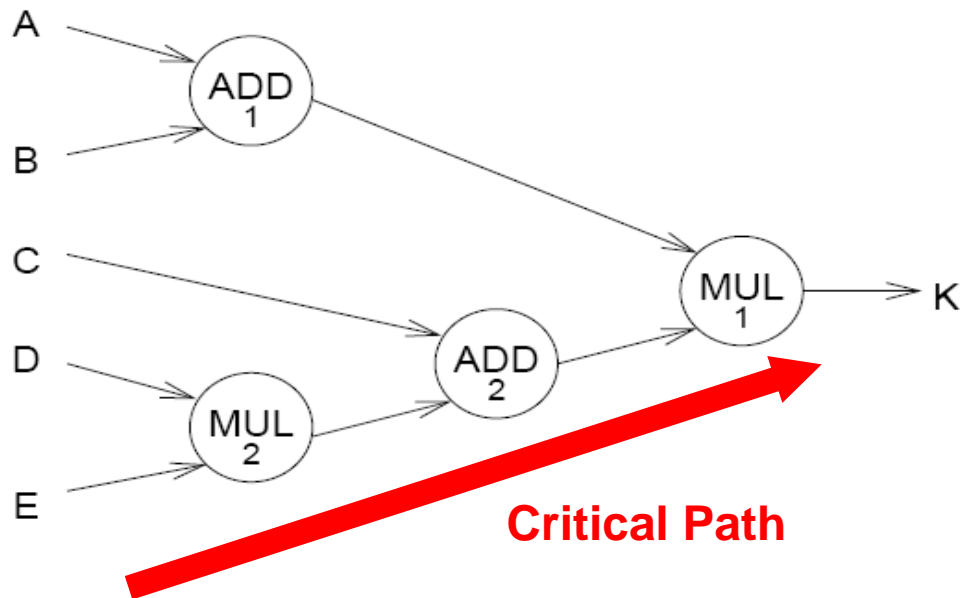
$$250 + 250 \times 3 + 200 = 1.2\text{ns}$$

$$f = 833\text{MHz}$$



Critical path

- ...begin to explore the construction of digital systems with complex behavior
 - Example: $K = (A +_1 B) * _1 (C +_2 D * _2 E)$
- Combinational circuit:



Thanks

